

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Nawalage Florence COORAY

Serial No.

Group Art Unit:

Confirmation No.

Filed: June 28, 2001

Examiner:

For: THERMOSETTING FLUORINATED DIELECTRICS AND MULTILAYER CIRCUIT
BOARDS

#41A
10-2701

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Before calculation of the filing fee for the subject application, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please AMEND the pending claims and ADD new claims * in accordance with the
following:

3. (AS ONCE AMENDED HEREIN) A dielectric film obtained by heat curing a
thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1.

4. (AS ONCE AMENDED HEREIN) A process for producing a dielectric film
comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer
according to claim 1.

6. (AS NEW HEREIN) A dielectric film obtained by heat curing a thermally curable
fluorinated o-aminophenol polymer or oligomer according to claim 2.

7. (AS NEW HEREIN) A process for producing a dielectric film comprising heat
curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

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A1

A2